

S/N Unknown

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Edward A. Schrock et al.

Examiner: ~~Unknown~~ *GR*

Serial No.: ~~Unknown~~ 09/649827

Group Art Unit: ~~Unknown~~ 733

Filed: ~~Herewith~~ 08-29-2000

Docket: 303.527US2

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

JCE10 U.S. PTO  
09/649827  
08/29/00

**INFORMATION DISCLOSURE STATEMENT**

# 2

Commissioner for Patents  
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for review in connection with the above-identified patent application. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner be returned to the Applicants.

In accordance with 37 C.F.R. §1.98(d), copies of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 09/227,942, filed on January 11, 1999, which is relied upon for an earlier filing date under 35 U.S.C. §120.

Applicants respectfully request consideration of these references during prosecution of the above-identified matter. The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

EDWARD A. SCHROCK ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 359-3276

Date Aug. 29, 2000

By

*Catherine I. Klima-Silberg*

Catherine I. Klima-Silberg

Reg. No. 40,052

"Express Mail" mailing label number: EL517792744US

Date of Deposit: August 29, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.